

## Single diode Power Module

**$V_{CES} = 400V$**   
 **$I_C = 500A @ T_c = 80^\circ C$**

### Application

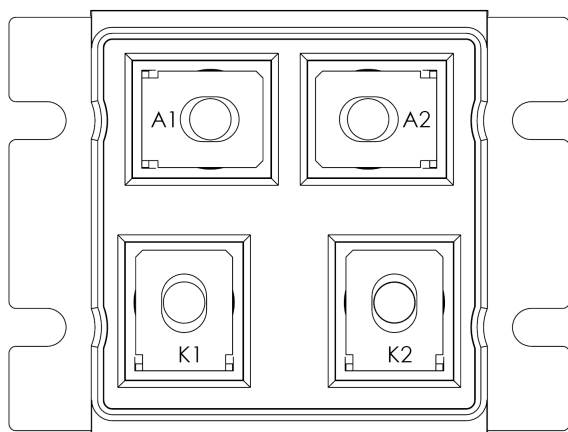
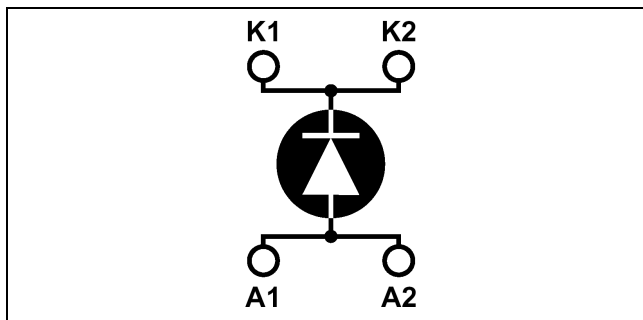
- Anti-Parallel diode
  - Switchmode Power Supply
  - Inverters
- Snubber diode
- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers
- Electric vehicles

### Features

- Ultra fast recovery times
- Soft recovery characteristics
- Very low stray inductance
- High blocking voltage
- High current
- Low leakage current

### Benefits

- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant



**All ratings @  $T_j = 25^\circ C$  unless otherwise specified**

### Absolute maximum ratings

<i>Symbol</i>	<i>Parameter</i>			<i>Max ratings</i>	<i>Unit</i>
V <sub>R</sub>	DC reverse Voltage			400	V
V <sub>RRM</sub>	Peak Repetitive Reverse Voltage				
I <sub>F(AV)</sub>	Average Forward Current	Duty cycle = 50%	T <sub>c</sub> = 25°C	500	A
			T <sub>c</sub> = 80°C	500	
I <sub>F(RMS)</sub>	RMS Forward Current			850	
I <sub>FSM</sub>	Non-Repetitive Forward Surge Current		T <sub>j</sub> = 25°C	5000	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed

**Electrical Characteristics**

<i>Symbol</i>	<i>Characteristic</i>	<i>Test Conditions</i>		<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
$V_F$	Diode Forward Voltage	$I_F = 500A$			1.3	1.5	V
		$I_F = 1000A$			1.6		
		$I_F = 500A$	$T_j = 125^{\circ}C$		1.2		
$I_{RM}$	Maximum Reverse Leakage Current	$V_R = 400V$	$T_j = 25^{\circ}C$			2000	$\mu A$
			$T_j = 125^{\circ}C$			5000	
$C_T$	Junction Capacitance	$V_R = 200V$			1300		pF

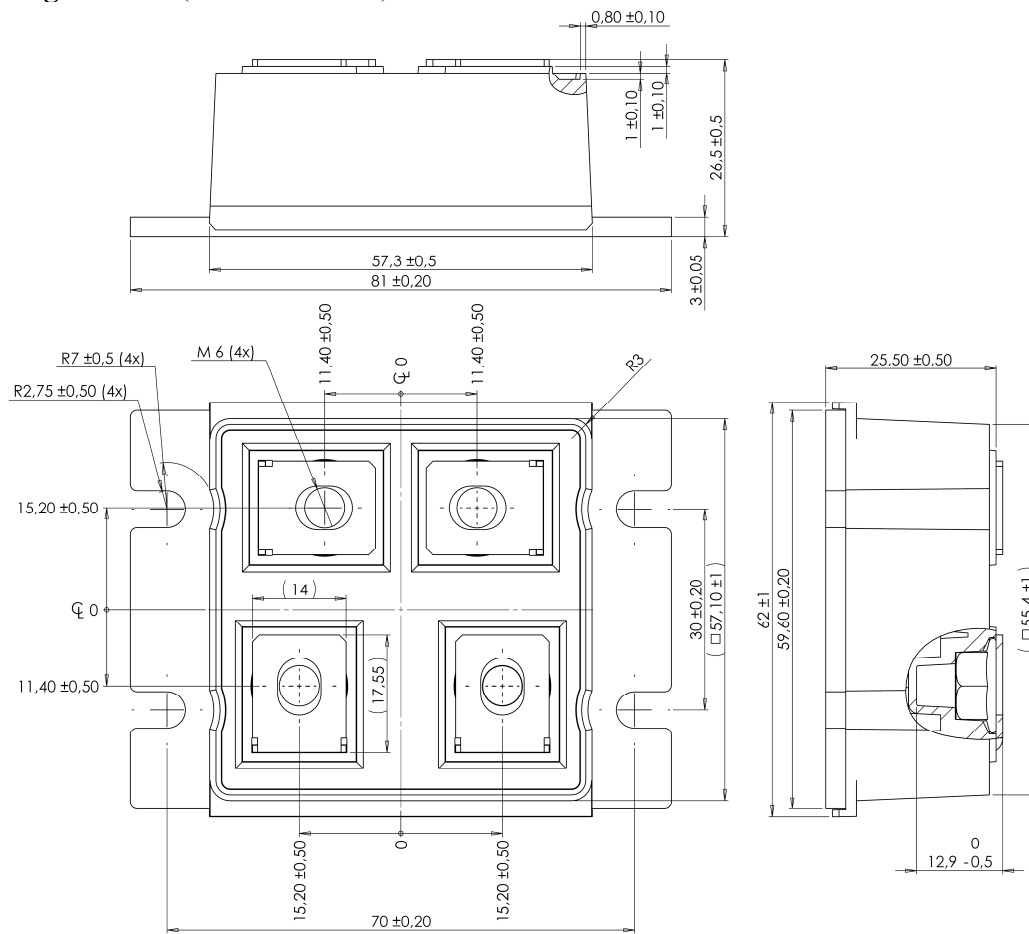
**Dynamic Characteristics**

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 500A V <sub>R</sub> = 268V di/dt=1000A/μs	T <sub>j</sub> = 25°C		50		ns
			T <sub>j</sub> = 125°C		150		
Q <sub>rr</sub>	Reverse Recovery Charge		T <sub>j</sub> = 25°C		750		nC
			T <sub>j</sub> = 125°C		5250		
I <sub>rr</sub>	Reverse Recovery Current		T <sub>j</sub> = 25°C		30		A
			T <sub>j</sub> = 125°C		65		
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 500A V <sub>R</sub> = 268V di/dt=4000A/μs	T <sub>j</sub> = 125°C		90		ns
Q <sub>rr</sub>	Reverse Recovery Charge				10.5		μC
I <sub>rr</sub>	Reverse Recovery Current				195		A

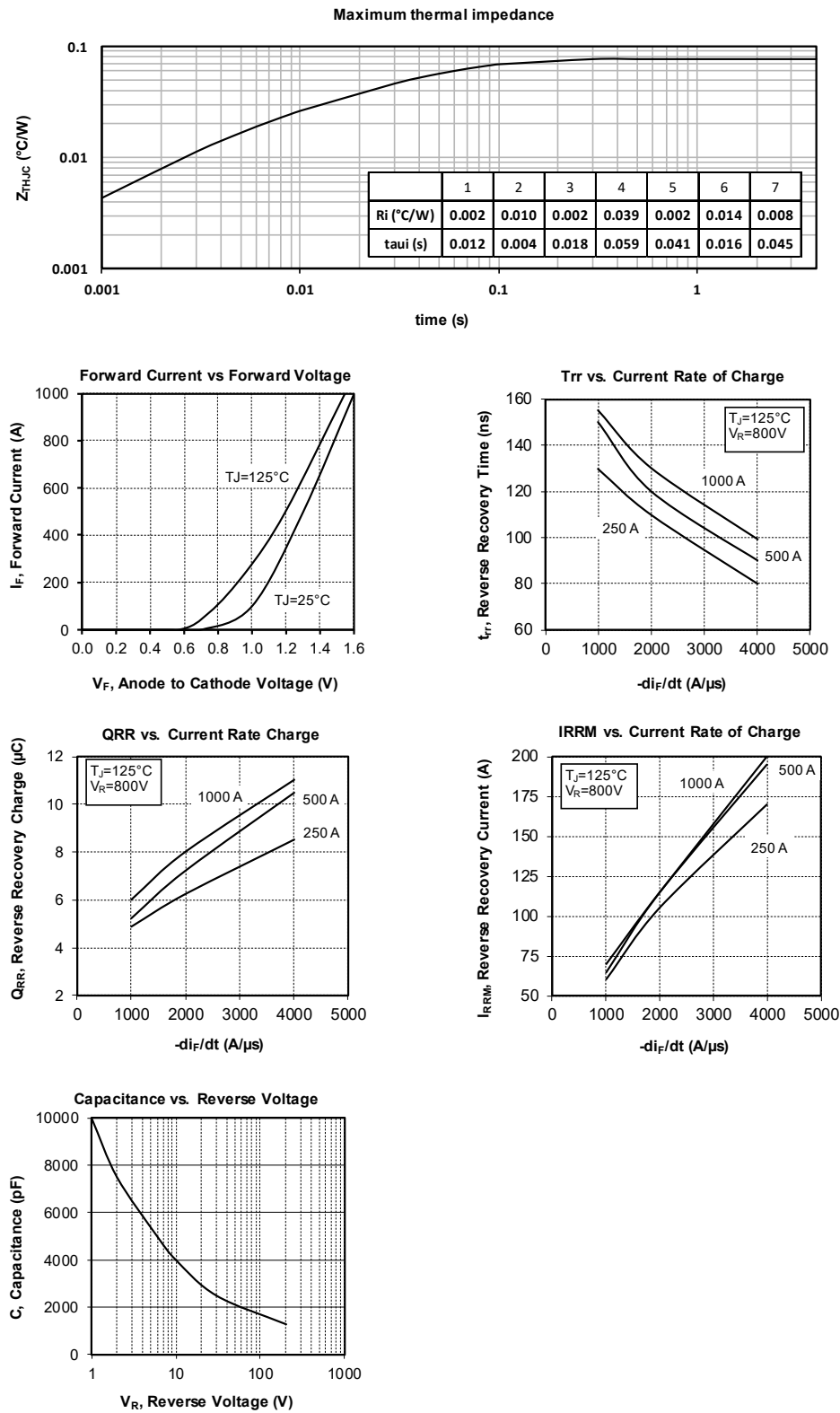
**Thermal and package characteristics**

Symbol	Characteristic			Min	Max	Unit
R <sub>thJC</sub>	Junction to Case Thermal Resistance				0.08	°C/W
V <sub>ISOL</sub>	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000		V
T <sub>J</sub>	Operating junction temperature range			-40	150	°C
T <sub>JOP</sub>	Recommended junction temperature under switching conditions			-40	T <sub>Jmax</sub> -25	
T <sub>STG</sub>	Storage Temperature Range			-40	125	
T <sub>C</sub>	Operating Case Temperature			-40	125	
Torque	Mounting torque	To heatsink	M5	2.5	3.5	N.m
		For terminals	M6	3	4	
Wt	Package Weight				250	g

### LP4 Package outline (dimensions in mm)



## Typical Performance Curve



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